1 Package summary

<table>
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<th>Parameter</th>
<th>Min</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
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<td>1.5</td>
<td>1.6</td>
<td>1.7</td>
<td>mm</td>
</tr>
<tr>
<td>package width</td>
<td>1.5</td>
<td>1.6</td>
<td>1.7</td>
<td>mm</td>
</tr>
<tr>
<td>seated height</td>
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<td>0.48</td>
<td>0.5</td>
<td>mm</td>
</tr>
<tr>
<td>nominal pitch</td>
<td>-</td>
<td>0.5</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>actual quantity of termination</td>
<td>-</td>
<td>6</td>
<td>-</td>
<td>-</td>
</tr>
</tbody>
</table>
2 Package outline

HXSON6: plastic, thermal enhanced extremely thin small outline package; no leads; 6 terminals; body 1.6 x 1.6 x 0.5 mm

Figure 1. Package outline DFN1616-6 (SOT1189-1)
3 Soldering

Footprint information for reflow soldering of HXSON6 package

Figure 2. Reflow soldering footprint for DFN1616-6 (SOT1189-1)
4 Legal information

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